2.5 Volt Reference

The NCV1009 is a precision trimmed 2.5 V \pm 5.0 mV shunt regulator diode. The low dynamic impedance and wide operating current range enhances its versatility. The tight reference tolerance is achieved by on–chip trimming which minimizes voltage tolerance and temperature drift.

A third terminal allows the reference voltage to be adjusted $\pm 5.0\%$ to calibrate out system errors. In many applications, the NCV1009Z can be used as a pin-to-pin replacement of the LT1009CZ and the LM136Z-2.5 with the external trim network eliminated.

Features

- 0.2% Initial Tolerance Max.
- Guaranteed Temperature Stability
- Maximum 0.6 Ω Dynamic Impedance
- Wide Operating Current Range
- Directly Interchangeable with LT1009 and LM136 for Improved Performance
- No Adjustments Needed for Minimum Temperature Coefficient
- Meets Mil Std 883C ESD Requirements
- Extended Operating Temperature Range for Use in Automotive Applications

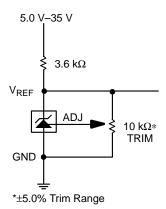


Figure 1. Application Diagram



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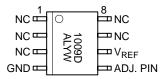


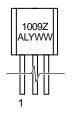
SO-8 D SUFFIX CASE 751



TO-92 Z SUFFIX CASE 29

PIN CONNECTIONS AND MARKING DIAGRAM





Pin 1. ADJ. PIN 2. V_{REF} 3. GND

A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

ORDERING INFORMATION

Device	Package	Shipping
NCV1009D	SO-8	95 Units/Rail
NCV1009DR2	SO-8	2500 Tape & Reel
NCV1009Z	TO-92	2000 Units
NCV1009ZRP	TO-92	2000 Tape & Reel

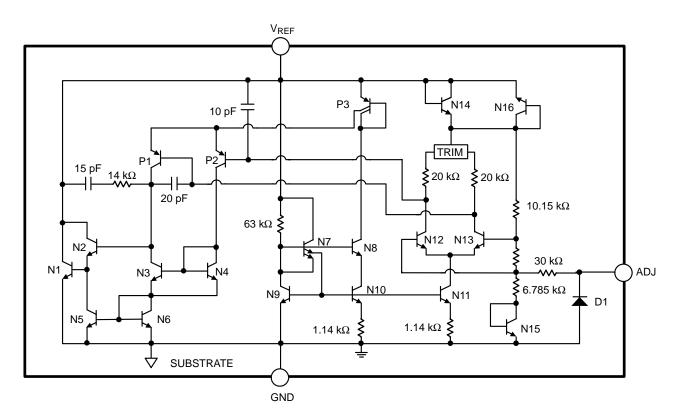


Figure 2. Block Diagram

MAXIMUM RATINGS*

Rating		Value	Unit
Reverse Current		20	mA
Forward		10	mA
Package Thermal Resistance, SO–8: Junction–to–Case, $R_{\theta JC}$ Junction–to–Ambient, $R_{\theta JA}$		45 165	°C/W
Package Thermal Resistance, TO-92: Junction-to-Case, R _{θJC} Junction-to-Ambient, R _{θJA}		_ 170	°C/W
Operating Temperature Range		-40 to +125	°C
Storage Temperature Range		-65 to +150	°C
Lead Temperature Soldering:	Wave Solder (through hole styles only) (Note 1) Reflow: (SMD styles only) (Note 2)	260 peak 230 peak	°C

¹⁰ second maximum

ELECTRICAL CHARACTERISTICS $(T_A = 25^{\circ}C)$ unless otherwise specified.)

Characteristic	Test Conditions		Min	Тур	Max	Unit
Reverse Breakdown Voltage	I _R = 1.0 mA		2.492	2.500	2.508	V
Reverse Breakdown Voltage	$0^{\circ}C \le T_{A} \le 125^{\circ}C$		2.492	2.500	2.508	V
Reverse Breakdown Voltage	$-40^{\circ}\text{C} \le \text{T}_{\text{A}} \le 0^{\circ}\text{C}$		2.480	2.500	2.508	V
Reverse Breakdown Voltage Change with Current	400 μA ≤ I _R ≤ 10 mA	†	_ _	2.6 3.0	10 12	mV mV
Reverse Dynamic Impedance	I _R = 1.0 mA	†	_ _	0.2 0.4	1.0 1.4	Ω Ω
Temperature Stability Avgerage Temperature Coefficient	$0^{\circ}C \le T_A \le 70^{\circ}C$, Note 3 $0^{\circ}C \le T_A \le 70^{\circ}C$, Note 3		_ _	- -	- -	mV ppm/°C
Long Term Stabilty	$T_A = 25^{\circ}C \pm 0.1 \text{ C}, I_R = 1.0 \text{ mA}$		_	20	-	ppm/kHr

TYPICAL PERFORMANCE CHARACTERISTICS

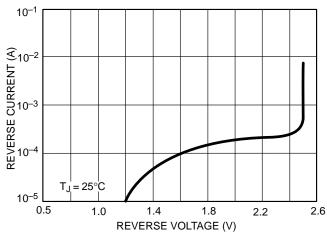


Figure 3. Reverse Current vs. Reverse Voltage

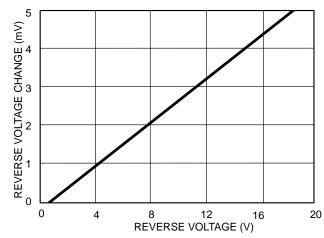
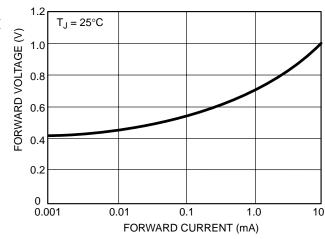


Figure 4. Change in Reverse Voltage vs. **Reverse Current**

^{2. 60} second maximum above 183°C.

^{*}The maximum package power dissipation must be observed.

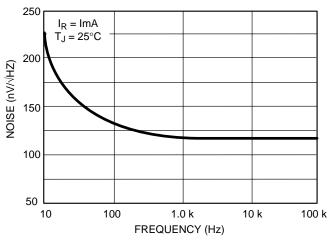
[†] Denotes the specifications which apply over full operating temperature range.3. Average temperature coefficient is defined as the total voltage change divided by the specified temperature range.



100 (G) HONED 10 0.1 10 100 1.0 k 10 k 100 k FREQUENCY (Hz)

Figure 5. Forward Voltage vs. Forward Current

Figure 6. Dynamic Impedance vs. Frequency



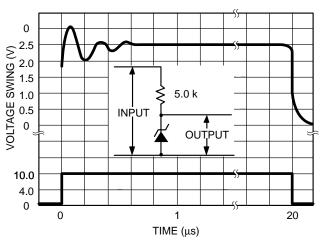
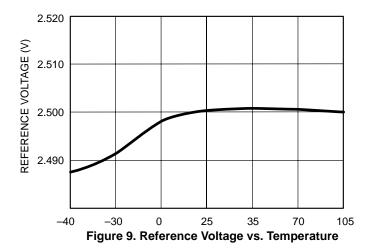


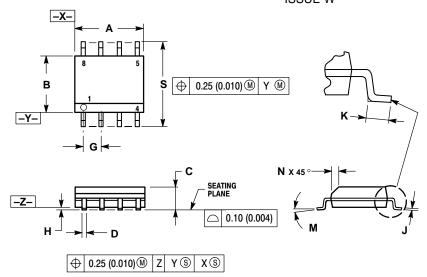
Figure 7. Zener Noise Voltage vs. Frequency

Figure 8. Response Time



PACKAGE DIMENSIONS

SO-8 **D SUFFIX** CASE 751-07 **ISSUE W**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

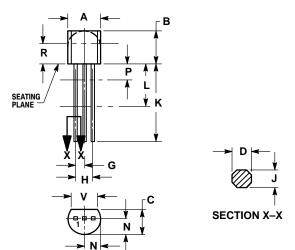
 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.

 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN
 EXCESS OF THE D DIMENSION AT MAXIMUM
 MATERIAL CONDITION.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27 BSC		0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016	0.050	
M	0 °	8 °	0 °	8 °	
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

TO-92 **Z SUFFIX** CASE 29-11 **ISSUE AL**



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.

 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
P		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	

Notes

Notes

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